ProLight PY2B-3FWE-WFCH
3W Power LED
Technical Datasheet
Version: 1.1

ProLight PEC2.0+ 1717 Series

For HUD Only

Features

· RoHS compliant
· Thinner product with Pad Extension Chip technology
· Flip chip technology

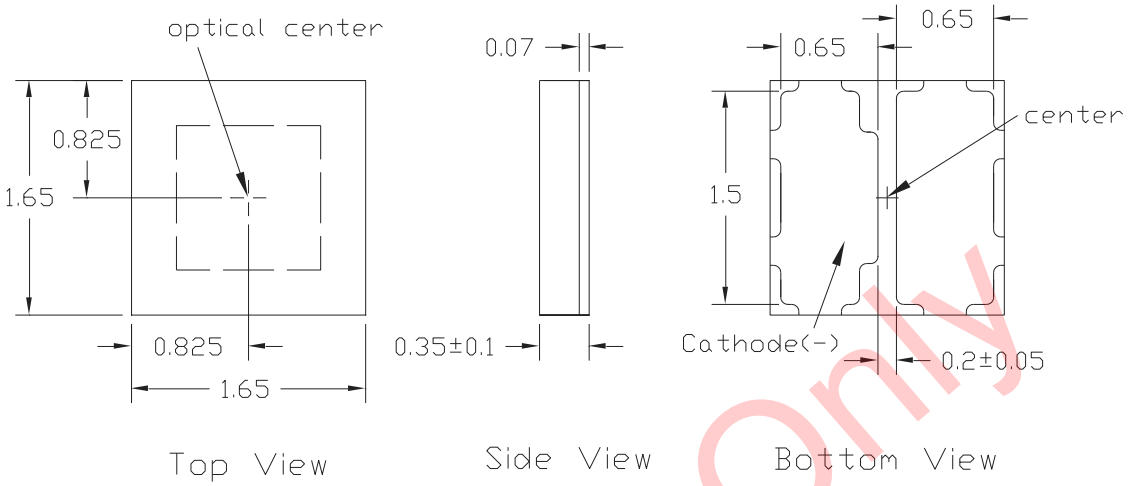
Main Applications

· Head up display (HUD)

Introduction

· ProLight 1717 is one of the smallest and thinnest high power CSP LED footprint available by ProLight Opto, has offered extended solid-state lighting design possibilities. The 1717's combination of consistent design across all configurations and its small size permit improved color mixing and optical control, compared to the larger 3535 LED. ProLight 1717 is designed with ProLight unique packaging and super thin substrate technology which providing superior high stability reliability.
· 1717 qualifies as the JEDEC Level 1 MSL sensitivity level and suitable for SMD process, Pb free reflow soldering capability, and full compliance with EU education of Hazardous Substances (RoHS) legislation.

Emitter Mechanical Dimensions



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Notes:
1. Drawing not to scale.
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are ± 0.1mm.
4. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
5. **Please do not use a force of over 0.3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

Flux Characteristics, T_J = 25˚C

Color	Part Number Emitter	Luminous Flux Φ_V (lm) @350mA Min.	@350mA Typ.	Refer @500mA Typ.	Refer @700mA Typ.
White	PY2B-3FWE-WFCH	100	140	185	240

- ProLight maintains a tolerance of ± 7% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics, T_J = 25˚C

Color	Forward Voltage V_F (V) @350mA Min.	@350mA Typ.	@350mA Max.	Refer @500mA Typ.	Refer @700mA Typ.	Thermal Resistance Junction to Slug (˚C/ W)
White	2.7	3.0	3.3	3.1	3.15	5

- ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

Optical Characteristics at 350mA, T_J = 25˚C

Radiation Pattern	Color	Color Temperature CCT Min.	Color Temperature CCT Typ.	Color Temperature CCT Max.	Viewing Angle (degrees) $2\theta_{1/2}$
Lambertian	White	-	12500 K	-	120

- ProLight maintains a tolerance of ± 5% for CCT measurements.

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Absolute Maximum Ratings

Parameter	White	
DC Forward Current (mA)	700	Refer @1000
Peak Pulsed Forward Current (mA)	1200 (less than 1/10 duty cycle@1KHz)	
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	2KV	
LED Junction Temperature	150°C	
Operating Temperature	-40°C - 125°C	-40°C - 95°C
Storage Temperature	-40°C - 125°C	-40°C - 95°C
Soldering Temperature	JEDEC 020c 260°C	
Allowable Reflow Cycles	3	
Reverse Voltage	Not designed to be driven in reverse bias	

Photometric Luminous Flux Bin Structure at 350mA

Color	Bin Code	Minimum Photometric Flux (lm)	Maximum Photometric Flux (lm)	Available Color Bins
White	U2	100	110	All
	V1	110	120	All
	V2	120	130	All
	W1	130	140	All
	W2	140	155	【1】
	X1	155	170	【1】
	X2	170	185	【1】

- ProLight maintains a tolerance of ± 7% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- 【1】The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Forward Voltage Bin Structure at 350mA

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
White	B	2.7	2.8
	D	2.8	2.9
	E	2.9	3.0
	F	3.0	3.1
	G	3.1	3.2
	H	3.2	3.3

- ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

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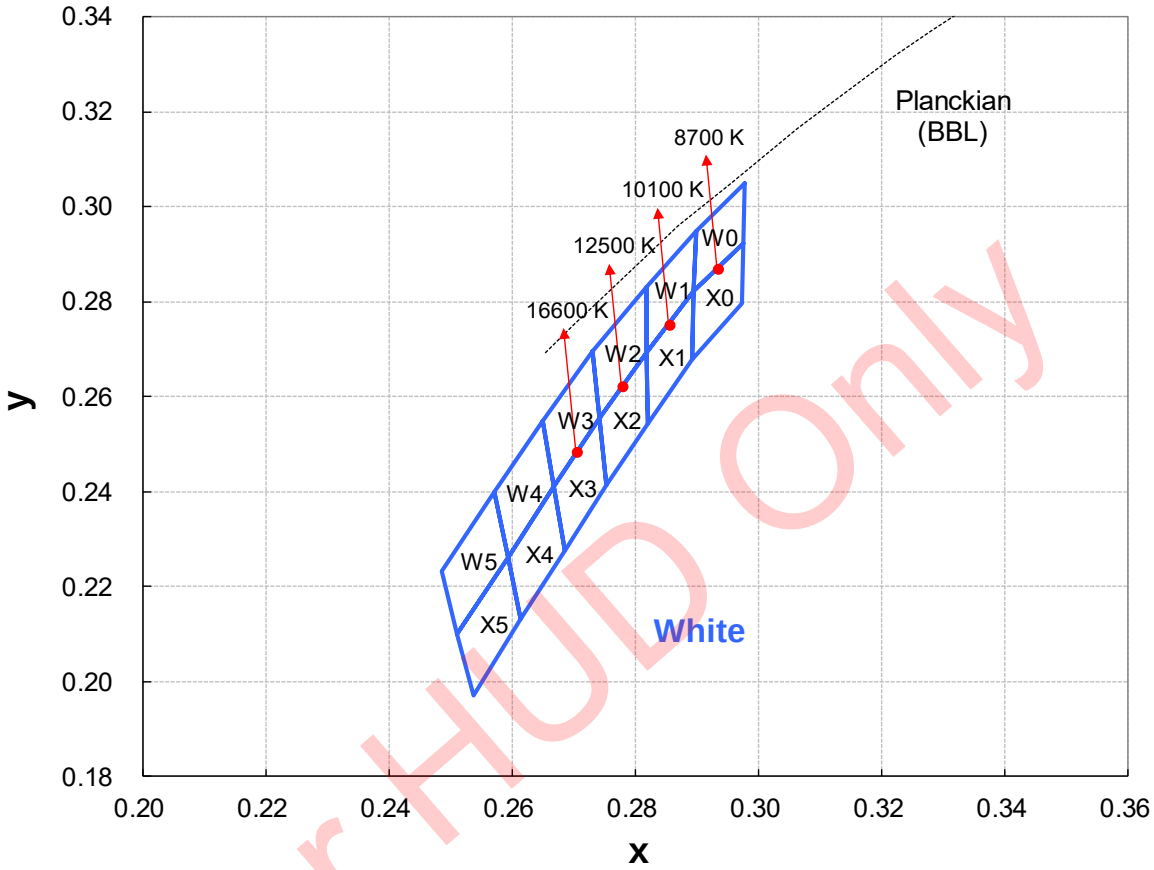
Color Bin

White Binning Structure Graphical Representation



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Color Bin

White Bin Structure

Bin Code	x	y	Typ. CCT (K)	Bin Code	x	y	Typ. CCT (K)
W0	0.2978	0.3051	-	W3	0.2731	0.2696	-
	0.2975	0.2924			0.2741	0.2555	
	0.2895	0.2823			0.2668	0.2410	
	0.2898	0.2950			0.2650	0.2550	
X0	0.2975	0.2924	-	X3	0.2741	0.2555	-
	0.2972	0.2796			0.2753	0.2413	
	0.2892	0.2680			0.2685	0.2275	
	0.2895	0.2823			0.2668	0.2410	
W1	0.2898	0.2950	-	W4	0.2650	0.2550	-
	0.2895	0.2823			0.2668	0.2410	
	0.2819	0.2693			0.2593	0.2260	
	0.2818	0.2831			0.2570	0.2400	
X1	0.2895	0.2823	-	X4	0.2668	0.2410	-
	0.2892	0.2680			0.2685	0.2275	
	0.2820	0.2544			0.2614	0.2133	
	0.2819	0.2693			0.2593	0.2260	
W2	0.2818	0.2831	-	W5	0.2593	0.2260	-
	0.2819	0.2693			0.2510	0.2100	
	0.2741	0.2555			0.2486	0.2234	
	0.2731	0.2696			0.2570	0.2400	
X2	0.2819	0.2693	-	X5	0.2593	0.2260	-
	0.2820	0.2544			0.2510	0.2100	
	0.2753	0.2413			0.2537	0.1970	
	0.2741	0.2555			0.2614	0.2133	

- Tolerance on each color bin (x , y) is ± 0.005

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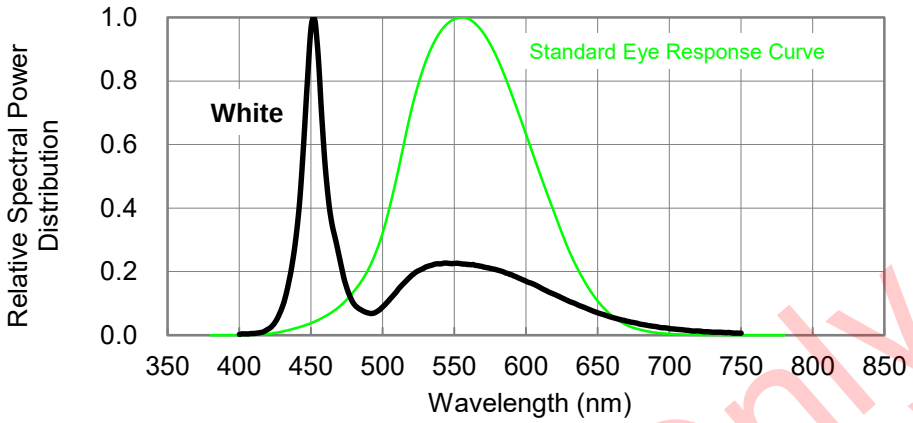
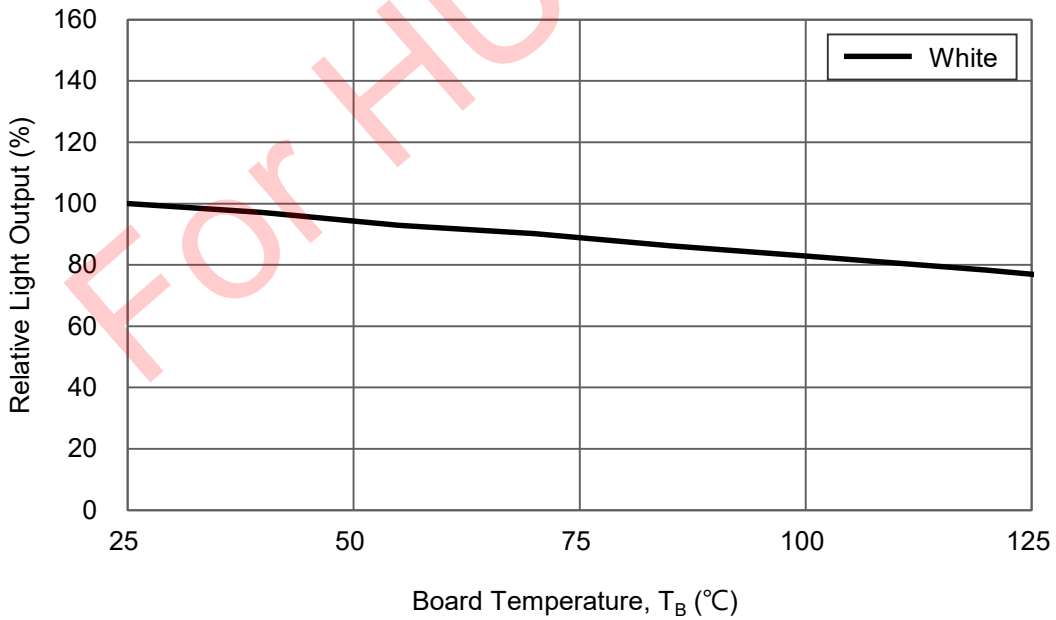
Color Spectrum, T_J = 25˚C

1. White



Light Output Characteristics

Relative Light Output vs. Board Temperature at 350mA



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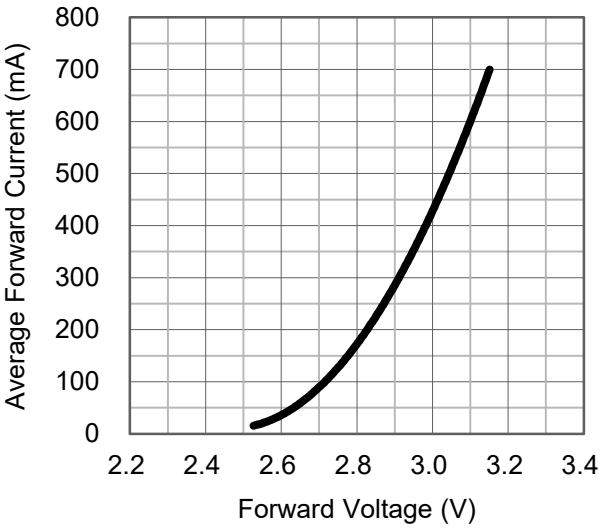
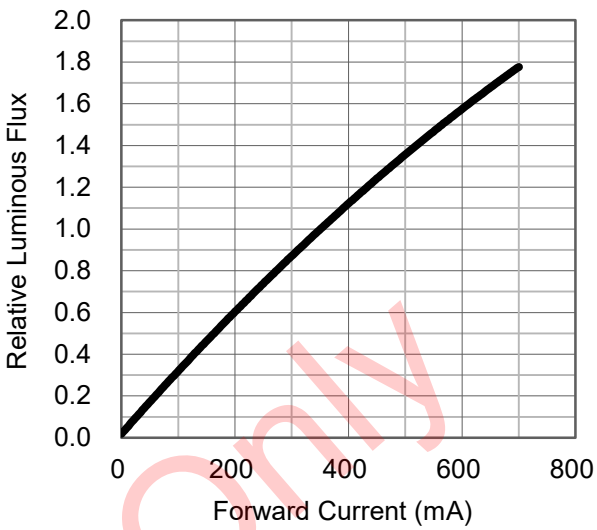
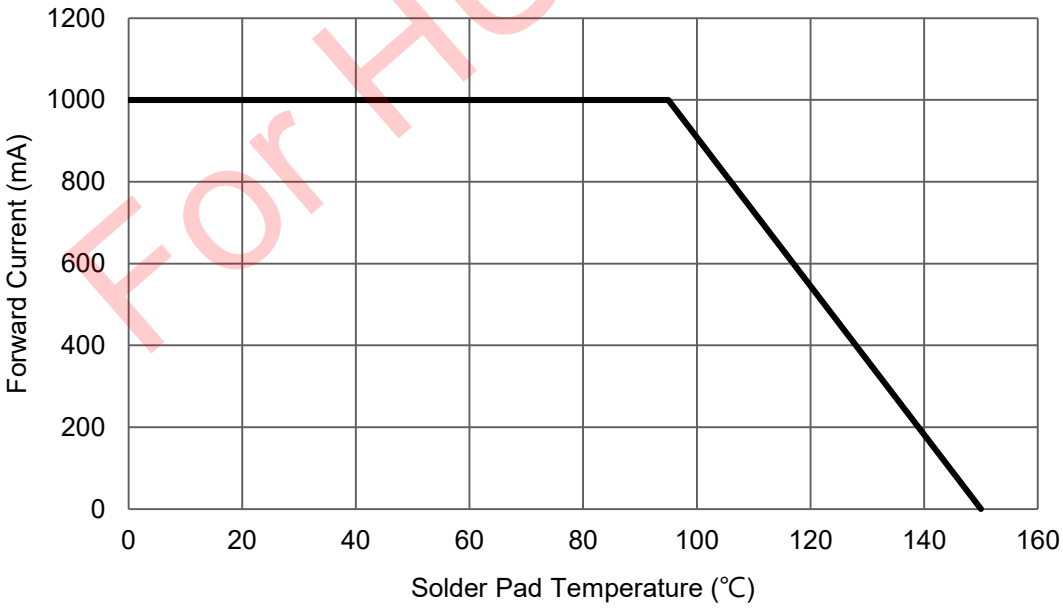
Forward Current Characteristics, T_J = 25˚C





Solder Pad Temperature vs. Maximum Forward Current



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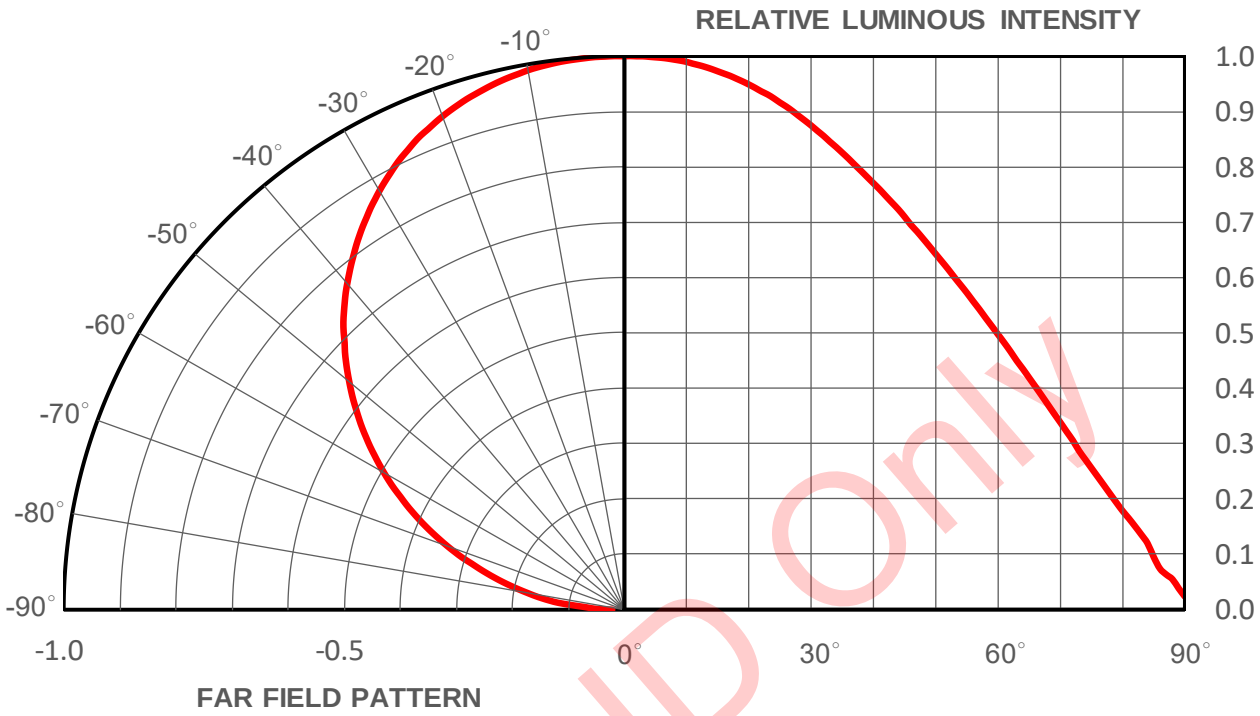
Typical Representative Spatial Radiation Pattern



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Moisture Sensitivity Level - JEDEC Level 1

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30˚C / 85% RH	168 +5/-0	85˚C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30˚C / 85% RH	168 +5/-0	85˚C / 85% RH	NA	NA
2	1 year	≤30˚C / 60% RH	168 +5/-0	85˚C / 60% RH	NA	NA
2a	4 weeks	≤30˚C / 60% RH	696 +5/-0	30˚C / 60% RH	120 +1/-0	60˚C / 60% RH
3	168 hours	≤30˚C / 60% RH	192 +5/-0	30˚C / 60% RH	40 +1/-0	60˚C / 60% RH
4	72 hours	≤30˚C / 60% RH	96 +2/-0	30˚C / 60% RH	20 +0.5/-0	60˚C / 60% RH
5	48 hours	≤30˚C / 60% RH	72 +2/-0	30˚C / 60% RH	15 +0.5/-0	60˚C / 60% RH
5a	24 hours	≤30˚C / 60% RH	48 +2/-0	30˚C / 60% RH	10 +0.5/-0	60˚C / 60% RH
6	Time on Label (TOL)	≤30˚C / 60% RH	Time on Label (TOL)	30˚C / 60% RH	NA	NA

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Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:
1. Depending on the maximum derating curve.
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	I_F = max DC	--	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	I_F = max DC	Initial Level x 0.7	--
Reverse Current (I_R)	V_R = 5V	--	50 μA

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

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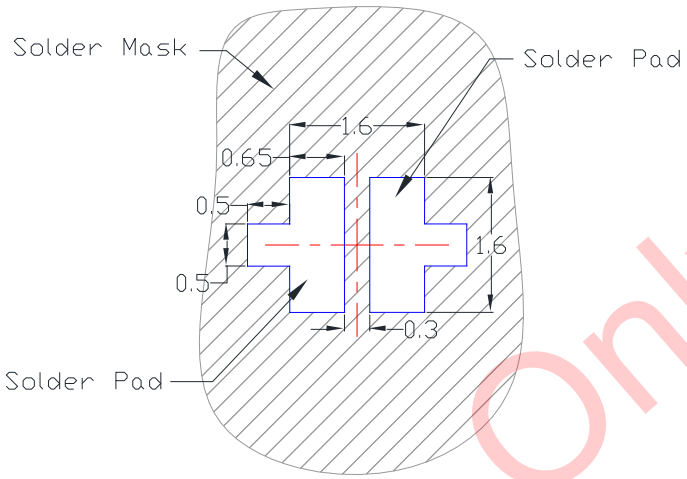
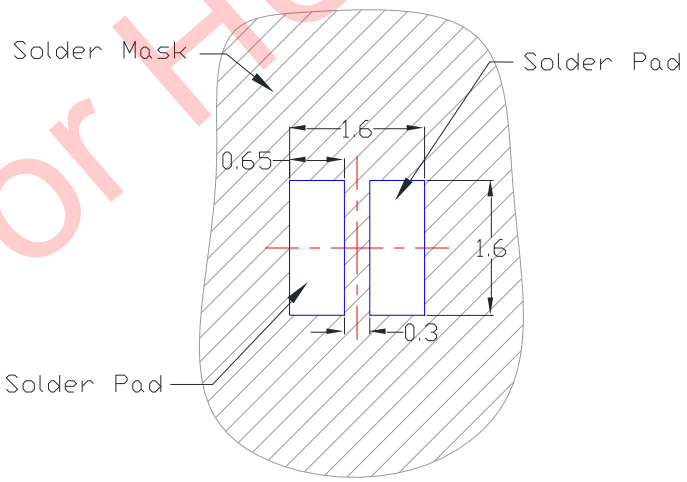
Recommended Solder Pad Design

Standard Emitter

TYPE A.



TYPE B.



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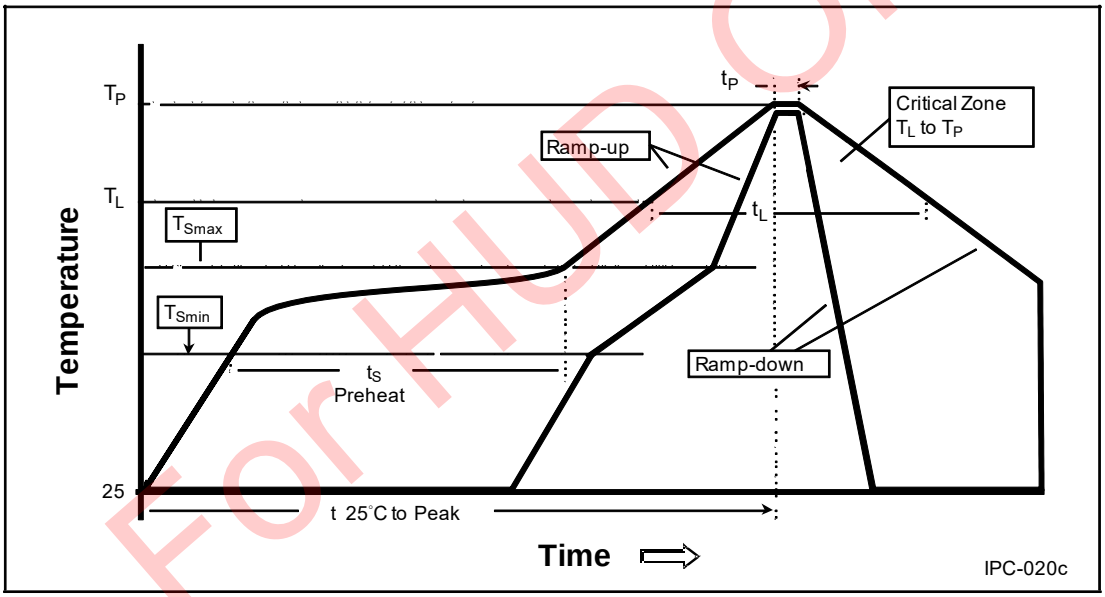
- All dimensions are in millimeters.

Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_P)	3°C / second max.	3°C / second max.
Preheat – Temperature Min (T_{Smin}) – Temperature Max (T_{Smax}) – Time (t_{Smin} to t_{Smax})	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: – Temperature (T_L) – Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak/Classification Temperature (T_P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_P)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



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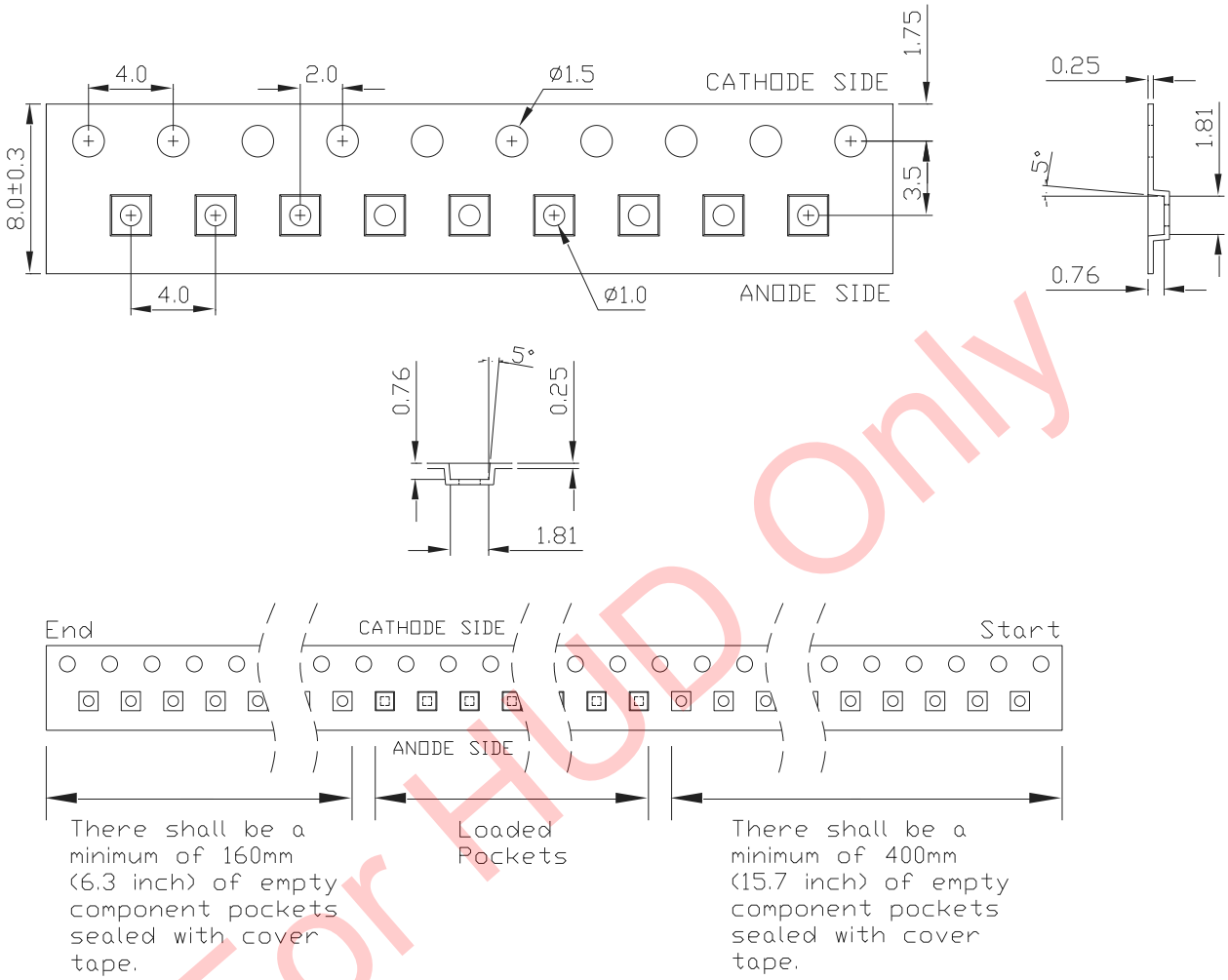
- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- **Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.**
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Reel Packaging



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Notes:
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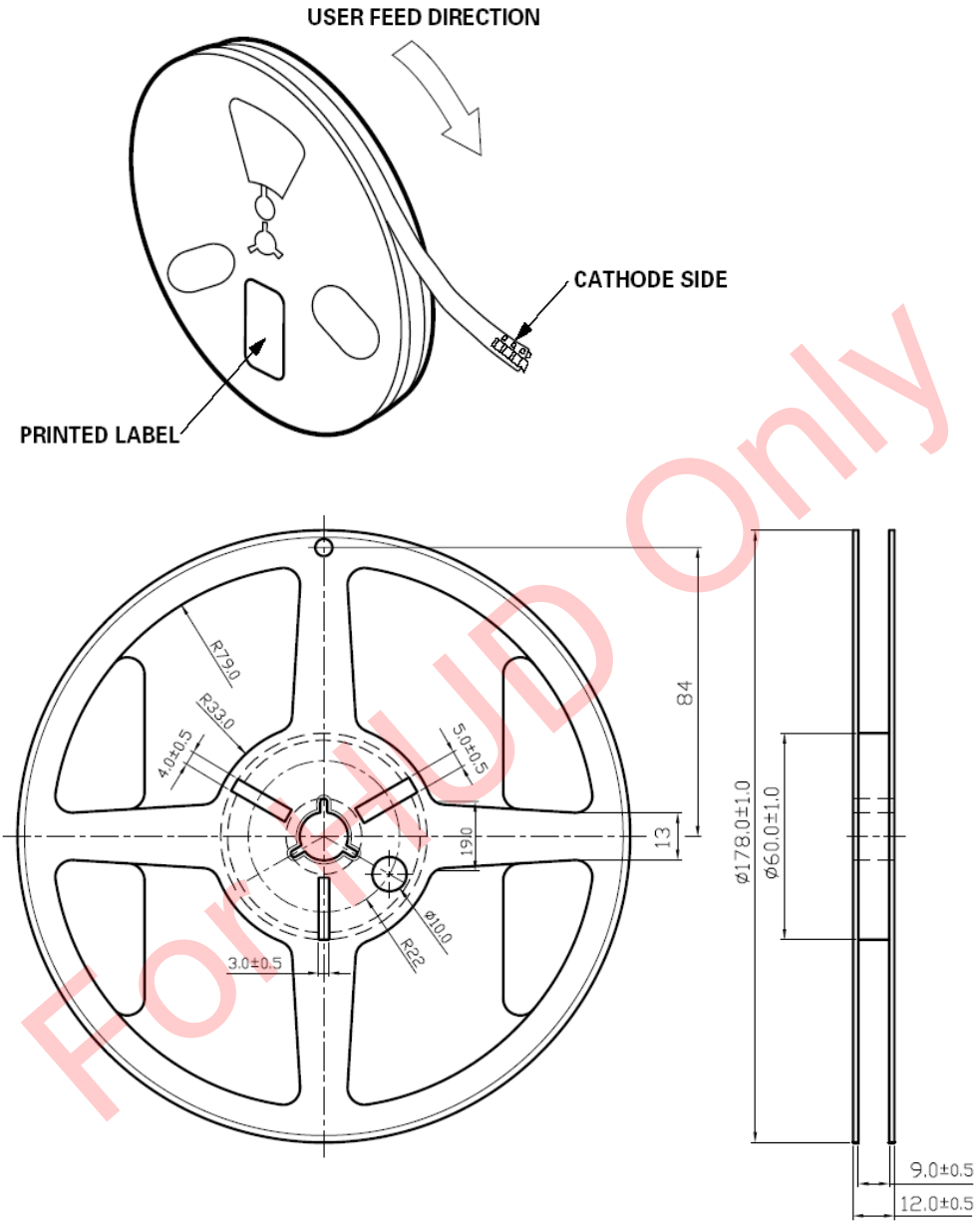
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are ± 0.1mm.

Emitter Reel Packaging



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Notes:
1. Empty component pockets sealed with top cover tape.
2. 1000 and 2000 pieces per reel.
3. Drawing not to scale.
4. All dimensions are in millimeters.

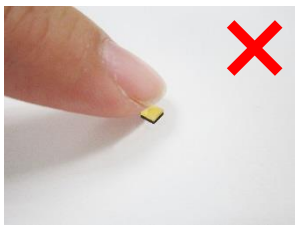
Precaution for Use

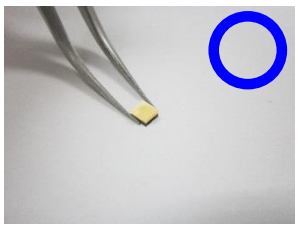
- Storage
  Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- **Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.**
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets.
  http://www.prolightopto.com/

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 0.3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)





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2. A critical component is any component of a life support device or system whose failure can reasonably be expected to cause the failure of the device or system, or to affect its safety or effectiveness.

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